CALL FOR PAPERS

TENCON is a premier international technical conference of IEEE Region 10, which comprises 57 Sections, 6 Councils, 21 Subsections, 514 Chapters and 1159 Student Branches in the Asia Pacific region. The theme for TENCON 2016 is Technologies for Smart Nation and it will be held in Singapore from 22-25 November, 2016.

This conference is expected to bring together researchers, educators, students, practitioners, technocrats and policymakers from across academia, government, industry and non-governmental organizations to discuss, share and promote current works and recent accomplishments across all aspects of electrical, electronic and computer engineering, we well as information technology. Distinguished people will be invited to deliver keynote speeches and invited talks on trends and significant advances in the emerging technologies.

The online electronic paper submission will open from March 1, 2016. The scope of conference papers and exhibits include but not limited to the following areas:

- Power Generation, Transmission and Distribution
- Power Electronics
- Wireless Power Transfer and Energy Harvesting
- Renewable Energy Sources and Technology
- Signal and Image Processing
- Antennas, Propagation and Computational EM
- Analog and Mixed Signal ICs
- RF/Millimeter-wave Circuits and Systems
- Smart Nation and Internet of Things
- Robotics, Control, Instrumentation and Automation
- 3D Printing/Flexible Electronics
- Electronic Devices & Materials Processing
- Nano-electronics
- Wireless Communications and Networks
- Computing Architectures and Systems
- Network and Cyber-Security
- Photonic Technologies
- Computational Intelligence
- Big Data Analytics
- Humanitarian Technologies
- Aerospace Technology
- Marine and Offshore Engineering

TENCON 2016 will feature both invited and contributed papers. The best papers will be selected from the contributed papers for awards. The presented papers will be submitted to IEEE Xplore which is indexed by major databases. Prospective authors are invited to submit full papers that are three to four pages, with double column IEEE Conference format.